



INDIAN INSTITUTE OF TECHNOLOGY BOMBAY
MATERIALS MANAGEMENT DIVISION
Powai, Mumbai 400076.

(PR No. 1000042876)

(RFQ No.3600002887)

Technical Specification for Chip Fabrication

Sr. no	Item Description	Qty	Unit	Compliance (Yes/No)	Additional info. if any
1.	Chip Fabrication TSMC 65nm MS RF GP Shared Block Foundry: TSMC Technology:65nm Flavor: MS RF GP Area:1 mm X 1.5 mm Sample Quantity: 100 Warranty: 1year	1.5	EA		

<p>2.</p>	<p>Quik-Pak QFN100 Assembly (QP-QFN100-12MM-4MM) M14490</p> <ol style="list-style-type: none"> 1. Packaging type: QFN 2. Packaging body size: 12 mm X 12mm 3. Package Lead count: 100 4. Package Lead pitch: 0.4 mm 5. Package Assembly Qty:20 6. Testing will be performed in house in our lab. Since this is a proprietary chip, we do not want a third party to intervene in our testing. 7. In-vitro test capability of the chip along with electrical FPGA based fast testing (multi-channel simultaneous testing) – will be done in-house. 8. Physical verification (DRC, LVS, Antenna) will be performed in-house in our lab. Since this is a proprietary chip, we do not want a third party to intervene in the physical verification. 	<p>1</p>	<p>EA</p>		
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